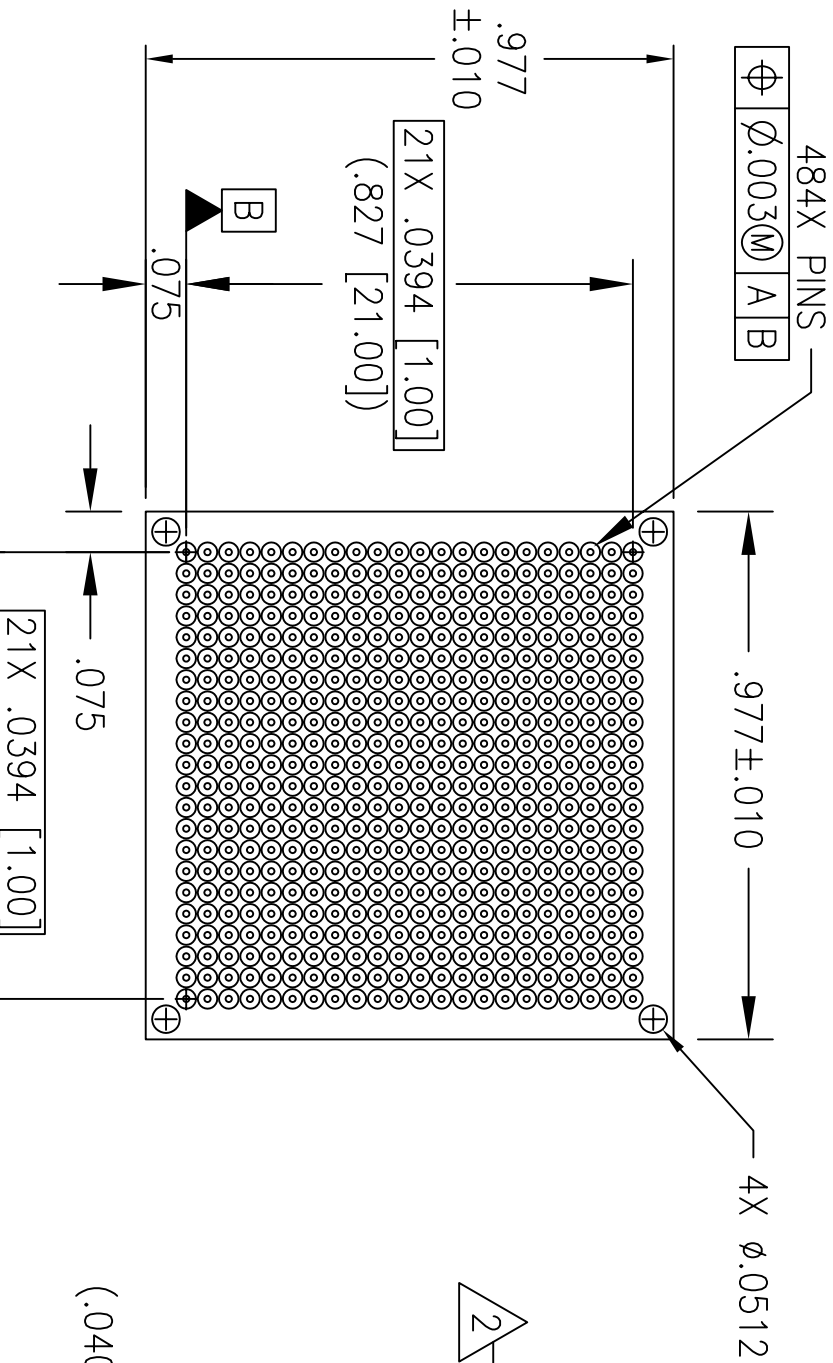


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REV	DESCRIPTION	ECN	DATE	RELEASE
1	SALES RELEASE			

TOP VIEW

RS VIEW



NOTES:

- 1. PINS  $\phi$ .0117  
MATERIAL: PHOSPHOR BRONZE.  
PLATING: HARD GOLD OVER NICKEL.
- 2. INSULATOR MATERIAL: FR4.

UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES TOLERANCES: ANGLES: ±1/64 FRACTIONS: ±.010 DECIMALS: .XXX ±.005 XXX ±.005		CONTRACT NO.	DATE	TITLE	SCALE	DRAWING NO.	REV
DESIGNER	DATE	DESIGNER	DATE	HILo-BGA PIN BASE 22 X 22, 484 PINS 1mm PITCH	N/A	HLP-220484-B-10	1
CHECKER	DATE	CHECKER	DATE	INTERCONNECT SYSTEMS INC. 708 VIA ALONDRA, CAMARILLO, CA 93012			
PROCESS ENG.	DATE	PROCESS ENG.	DATE				